# Monthly LabAdviser update: 30/6 2017

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| Updated Subject  | Contributor | Link to the updated pages |
| **ALD**ALD of SiO2ALD of AlNALD of HfO2ALD of TiN | **Tanja Amport @danchip** | [Thin\_film\_deposition/Deposition\_of\_Silicon\_Oxide](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silicon_Oxide) [Thin\_film\_deposition/Deposition\_of\_Aluminium\_Nitride](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Aluminium_Nitride)[Thin\_film\_deposition/Deposition\_of\_Hafnium\_Oxide](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Hafnium_Oxide) [Thin\_film\_deposition/Deposition\_of\_Titanium\_Nitride](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Titanium_Nitride)  |
| **Gold deposition**Thin Au layer on Lesker – the need for adhesion promoter | **Radu Malureanu****@danchip****Johneph Sukham @fotonik** | [Deposition\_of\_Gold#Thin\_Au\_layer\_deposition\_using\_Lesker](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Gold#Thin_Au_layer_deposition_using_Lesker) |
| **ASE in RIE mode**Si etching without wafer cooling | **Berit G. Herstrøm @danchip** | [Si\_etch\_using\_ASE#Etching\_Si\_without\_back\_side\_cooling](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Silicon/Si_etch_using_ASE#Etching_Si_without_back_side_cooling) |
| **3 week report****“PEALD deposition of AlN”** | **3-week students:****Asger Sommer****Christoffer Jensen****Rikke Bagge****Supervisors:****Pernille V. Larsen****Mikkel D. Mar****Tanja Amport****@danchip** | **Process2Share:**[http://www.process2share.danchip.dtu.dk/index.php/Projects,\_Theses\_and\_Papers/3-week\_courses](http://www.process2share.danchip.dtu.dk/index.php/Projects%2C_Theses_and_Papers/3-week_courses) |
| **Al2O3 dry etching in III-V ICP** | **Anpan Han @danchip** | [Etch/Aluminum\_Oxide/Al2O3\_Etch\_with\_III-V\_ICP](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Aluminum_Oxide/Al2O3_Etch_with_III-V_ICP) |

# Equipment Manuals updated in LabManager:

As an approved user on a piece of equipment you have to make sure you have read and understood the latest version of the manual before using the equipment.

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| **Manual for Imprinter 2** |
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| **Manual for Critical Point Dryer** |
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| **Manual for ASE** |
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| **Manual for Saw (Disco 321)** |
| **Manual for FilmTek** |
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